

ABSTRACT OF THE DISCLOSURE

5 A method of reducing package stress includes placing
matched components of an op-amp substantially in a region
of a die having the least stress gradients. The region is
located in the center of the die. Further, the center is
the common centroid of the die. The matched components are
10 the current mirror input stages of the op-amp. In one
embodiment, a semiconductor configuration includes a die
having a region with the least stress gradients, and an op-
amp containing matched components that are located
substantially in the region.

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